

**IEEE****IIT Roorkee**

Mini Colloquium on
Developments in Electroless Plating, Packaging and
Magnetoelectric Systems

Date: 7th November 2025

Timing: 09 AM to 05 PM

Venue & Mode: Offline at A.P.J. Abdul Kalam Block, Lecture Hall Complex, IIT Roorkee

Hosted by:

Prof. Sanjeev Manhas

Faculty Advisor, IEEE EDS Student Branch Chapter (SBC)

Head, Department of Electronics & Communication Engineering, IIT Roorkee

Fees:
Rs. 200/-



About the Colloquium

This colloquium will cover key topics including the fundamentals of electrical package design, thin-film metallization using electroless plating on glass substrates, and strain-mediated magnetoelectric devices for biomedical applications. Interactive demonstrations on 3D IC packaging of MEMS devices will further enhance participants' practical knowledge and interdisciplinary research insights.

Why You Should Attend

- **Advance Your Knowledge:** Explore cutting-edge research in plating, packaging, and magnetoelectric technologies.
- **IIT Roorkee Certification**
- **Networking:** Engage with leading researchers, faculty, and peers.
- **Expert Insights:** Learn from professors at IIT Roorkee, IIT Delhi, and IIT Bombay.
- **Research Opportunities:** Discover interdisciplinary applications across electronics, materials, and biomedical systems.

Demonstration & Discussion Session

The colloquium will also include demonstration and interactive sessions focused on:

Topic: 3D IC packaging of MEMS Devices

Invited Talks:



Prof. Pradeep Dixit

Department of Mechanical Engineering
IIT Bombay

Topic: Thin Film Metallization: Electroless plating on glass-based packaging.



Prof. Dhiman Mallick

Department of Electrical Engineering, IIT Delhi
Topic: Strain-mediated Magnetoelectric Heterostructure-based Devices for Biomedical Microsystems.



Prof. Anand Bulusu

Department of Electronics & Communication Engineering, IIT Roorkee

Topic: Circuit issues in Packaging.



Prof. Sanjeev Manhas

Professor & Head, Department of Electronics & Communication Engineering, IIT Roorkee

Topic: Fundamentals of Electrical Design of Packages

Who Should Attend

- Faculty members interested in semiconductor and microsystem research.
- Research scholars are pursuing work in related areas.
- Students eager to learn about modern Electronics Device Technologies.

How to make Payment

Please complete the payment using the provided QR code and upload the UPI payment screenshot while submitting the Google registration form through the link below.



IEEE EDS SBC IITR

Scan QR for
Payment

Lunch and refreshments
will be provided.

Registration Link

<https://forms.gle/odUH1Lyk7ycX3QKNA>

Reach Us :

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